員享

ALPHA REFERENCE NO. SP08120131

SPECIFICATION

1. RA4520F-20-15C2-A10K	PART NO.	ALPHA MODEL NAME
	1.	RA4520F-20-15C2-A10K
		*

MODEL NAME

MODEL NO.

APPROVAL



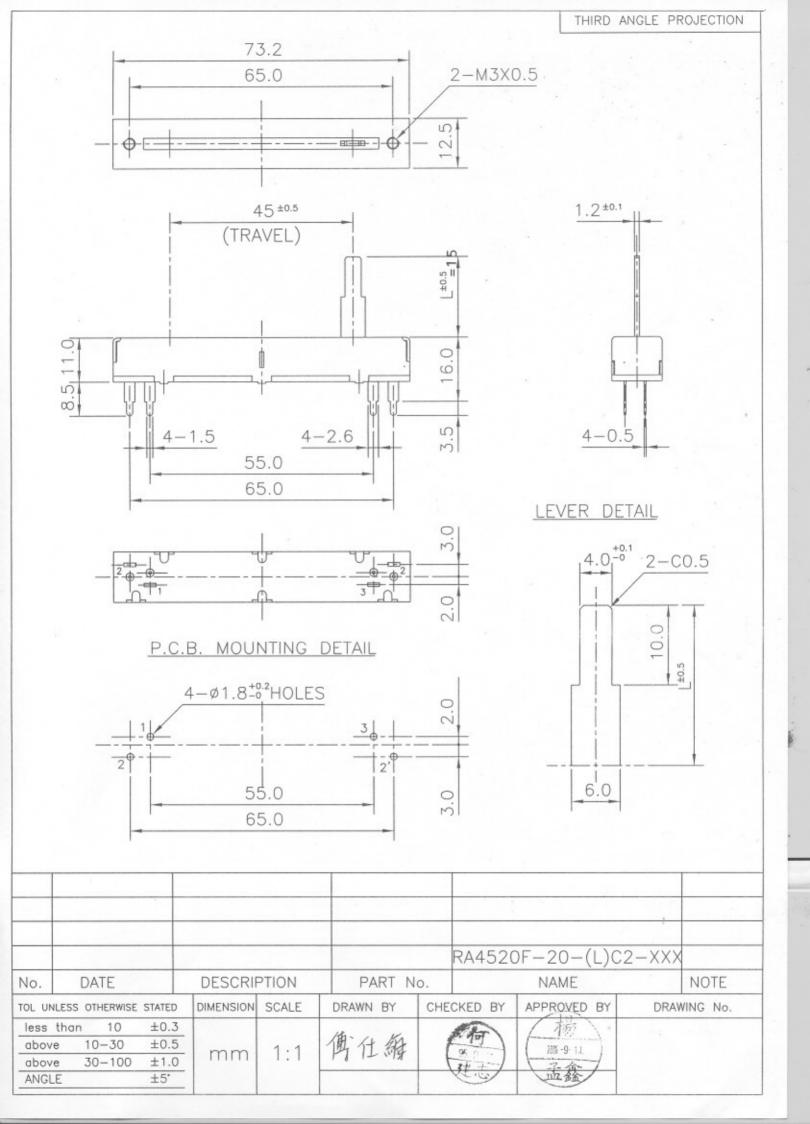


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TAIWAN ALPHA ELECTRONIC CO., LTD.

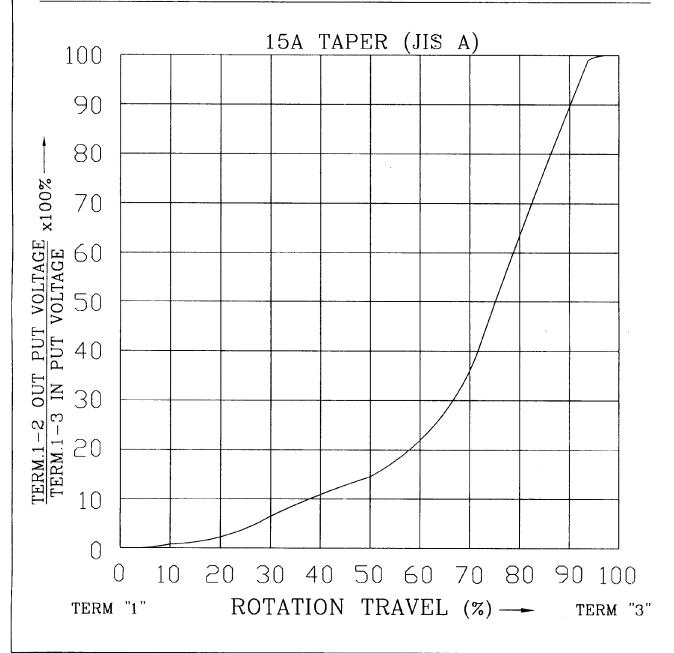
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CUSTOMER'S NAME 員享						DATE DE	C.11.2008	
1. MECHANICAL SPECIFICATION				2. ELECTRICAL SPECIFICATION				
append f	ig.			1. OVERALL RESISTANCE & TOLERANCE	terminal 1-3	10K	Ω± 20	%
degree)		±5°	2. TAP RESISTANCE & TOLERANCE	terminal 1-4		Ω±	%
mm		45	±0.	3. RATED WATTAGE	temp 0~50°C		0.125	W
twisting mo	ment	less than	kg.cm 4. MAXIMUM WORKING VOLTAGE				250	V
torsional mo	oment	less than	2 kg.cı	5. RESISTANCE TAPER MEASURING POINT		Α :	50 %po	int
speed 60 de	g/sec.	g.cm		& TOLERANCE		10	~ 25	%
speed 20mm/sec			0 g.c	6. RESIDUAL RESISTANCE	terminal 1/3 side	less that	n 20/20	Ω
pulling pus	shing	more than kg		7. TAP RESIDUAL RESISTANCE	terminal 4 side	less that	n 100	Ω
within m	m (bending	g moment	moment g.cm) 8. SLIDE NOISE				n 47	mV
	•)		more than 100	MΩ(DC	500	V)
				10. WITHSTAND VOLTAGE	AC 500	V	1 min	iute
			sec	11. TRACKING ERROR				
<u> </u>	.IIII ± 2%			12. SWITCH CONTACT RESISTANCE	МΩ	less than	m	nΩ
_	nm)			13. SWITCH RATING				
, ,						•		
14. SWITCH WORKING TORQUE (FORCE) g.cm 15. SWITCH CIRCUIT				- 3. USABLE TEMPERATURE RANG	E: from –10°C to	o 70°C		
				$^{\perp}$ 4. VR LIFE 15,000 \pm T	IMES			
				RESISTANCE CH	HANGE: within:	±	%	
				SLIDE NOISE : le	ess than		mV	
	DIMEN							
at M	L	F	T			an	m	\circ
	15			CONTACT RESIG	JIANCE. ICSS (II	an	•••	22
MODEL NAME DRA				REFERENCE NO.		R	EV	
RA4520F-20-15C2-A10K			<u> </u>	SP08120131				
	append for degree mm twisting more than 500 soldering heat 350 resist change with g.cm OT at M degree mm twisting more than 500 soldering heat 350 resist change with g.cm	append fig. degree mm twisting moment torsional moment speed 60 deg/sec. speed 20mm/sec pulling pushing within mm (bending more than 500 g.cm / 10 soldering heat 350±5°C/3sec. 2 resist change within ± 2% g.cm degree (mm) g.cm DIMEN At M L 15	append fig. degree mm 45 twisting moment less than torsional moment less than speed 60 deg/sec. speed 20mm/sec 50~35 pulling pushing more than within mm (bending moment more than 500 g.cm / 10 ± 1 sec soldering heat 350±5°C/3sec. 200g.cm/10 ±1; resist change within ± 2% g.cm degree (mm) g.cm DIMENSION at M L F 15 DRAWING No	## Append fig. degree	### PION append fig.	Properties Pro	DESCRIPTION Control of the property of the	DEC.11.2008 DEC.11.2008

STANDARD RESISTANCE TAPER



•									
NO.	NO. DATE DESCRIPTION				MODEL NAME				
TOL.	UNLESS OTHE	ERWISE STATED	DIMENSION	SCALE	DRAWN BY	CHECKED BY	APPROVED BY	DRAWING NO.	
abo abo abo	ve 30 -	10 ±0.3 - 30 ±0.5 -100 ±1.0 ±5°	mm		何 90.8.21 建志	王 90.8.21 茂松	至 90 8 21 茂松		

可變電阻無鉛焊錫共通規格書

Common Specification of Lead-Free Soldering for Potentiometers

以下焊錫條件以可變電阻置於單層 1.6mm 厚度之印刷電路板上測試爲基準.

The specification below is based on testing results of 1.6mm thickness single layer printed circuit board.

1. 手工焊錫條件:

For Manual Soldering:

1-1 操作溫度最高 350°C,操作時間 3 秒以內。

To be performed within 3 seconds at 350°C or below.

2. 自動或半自動機台焊錫條件:

For Automated or Semi-Automated Soldering Equipments:

2-1 使用發泡式且比重 0.82 以上的助焊劑,發泡高度以印刷電路板厚度一半為標準,且助焊劑 不能流入可變電阻基板表面及印刷電路板表面。

Flux of 0.82 specific gravity, applied by foam fluxer, shall be used. Foam head shall be limited to the height which is half thickness of printed circuit board to be soldered. No flux should be allowed to run up onto resistive element board of potentiometer and the surface of printed circuit board.

- 2-2 預熱時間不超過兩分鐘,焊錫接面 (即印刷電路板底) 最高預熱溫度不超過 100°C。

 Regarding preheating, the entire flow duration should not exceed 2 minutes, and soldering surface temperature (undersurface of PCB) shall be settled within 100°C.
- 2-3 焊錫過程機台設定溫度在 260°C 以下、 4 秒以內。

Solder Dipping is to be performed within 4 seconds at 260°C or below.

- 3. 若可變電阻爲帶有檔位,請將主軸或滑柄先調整至其中一個檔位或中心檔位上才可以進行焊錫作業。
 For potentiometer with centre detent or multiple detents, its shaft or lever should be settled in relevant detent position prior to soldering process.
- 4. 手工焊錫、自動或半自動機台焊錫不得超過一回。

Regardless of soldering facility and method, solder dipping or solder smearing must not be carried out more than 1 time.

註:本項焊錫溫度條件不適用於回流焊接作業設備。

Remarks: This specification is not recommended for and applicable in reflow soldering.